



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-HDBK-001 with Amendments 1 and 2

Handbook and Guide to Supplement J-STD-001 (Includes J-STD-001 B-C-D Comparisons)

Developed by the IPC-HDBK-001 Task Group (5-22F) of the Assembly and Joining Process Committee (5-20) of IPC

Users of this handbook are encouraged to participate in the development of future revisions.

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Handbook and Guide to Supplement J-STD-001

The following is referenced to J-STD-001C Clause numbers and includes J-STD-001B to C comparison.

See Table 1 for a cross reference by topic for J-STD-001 Revisions B-C-D and Table 2 for J-STD-001C to D comparison.

PREAMBLE/FOREWORD

This handbook, with Amendment 1, is a companion reference and comparison guide to J-STD-001B and IPC/EIA J-STD-001C. The amendment to IPC-HDBK-001 is to identify and incorporate changes as a result of J-STD-001 Revision C, including new material. Tables 1-1 (sorted in Revision B order) and 1-2 (sorted in Revision C order) will assist users with locating support information in this handbook and in identifying changes between the revisions.

With the present transition from prescriptive “how to” specifications to performance-based standards, much of the tutorial information that was provided in J-STD-001A was removed. While the main thrust of J-STD-001 remains process control in the assembly of products, the Scope of the Standard was revised, as were many technical requirements. The intent of this handbook is to capture the “how to” information and give more background for the specification limits and how they were derived. In addition, other supporting information is provided to give a broader understanding of the process considerations needed for the production of acceptable hardware. The target reader of this handbook is a process or manufacturing engineer.

FORMAT (Using This Handbook)

The section and paragraph numbers in this handbook refer and correspond to the section and paragraph numbers in J-STD-001B and/or IPC/EIA J-STD-001C, although subparagraph numbers of supporting material may not correspond exactly. J-STD-001B appendices that were removed from Revision C are included in this handbook. Information concerning the appendices in J-STD-001B is either addressed in the body of this handbook or, in the case of Appendix D, covered more thoroughly in another document. An appendices guide is included at the end of Section 13 that links the topics discussed in the appendices of J-STD-001B to the appropriate supplemental information.

Where used verbatim, text that is directly quoted from a standard is identified by SMALL CASE CAPITAL LETTERS, with **must** and **shall** annotated in bold. If it is new or has changed in IPC/EIA J-STD-001C, it is also *ITALICIZED*.

For the purposes of this handbook, a capitalized “Standard” in the handbook text refers to both J-STD-001B and IPC/EIA J-STD-001C. Text unique to only one of the revisions is in a half page column and is identified by either [J-STD-001B] or [IPC/EIA J-STD-001C] at the top of each column. By default, if there is no revision designator and the text flows across the whole page, it applies to both revisions.

Note: References in the text of this handbook (not text quoted from a Standard) refer only to sections, tables, and figures in this handbook unless otherwise noted (see Example 1). If the reference is to a section, table, or figure in either version a designator of the revision being referenced will follow it (see Example 2).

Example 1:

For more information on lead trimming, see 5.2.0.5.

Example 2:

For more information on defects, see Table 11-1 of J-STD-001B.

Endnotes are included in some sections to acknowledge references included in that section. Acronyms are used throughout the handbook and are defined in an Acronym Index at the end of this handbook.
